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**Nakamura**

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(54) **SEMICONDUCTOR MODULE**

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

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2021/04; H01L 21/4814; H01L 21/4846;  
H01L 21/4871; H01L 21/67144; H01L 23/12;  
H01L 23/13; H01L 23/14; H01L 23/147;  
H01L 2924/171; H01L 2924/1711; H01L  
2924/1715; H01L 2924/171151; H01L  
2924/181; H01L 2924/19042; H01L  
2224/08054; H01L 23/58; H05B 41/14;  
H05K 1/142; H05K 1/144; H05K 1/18;  
H05K 1/181; H05K 1/182; H05K 1/026  
USPC ..... D13/110, 182; 257/678, 684, 690, 691;  
361/679.01, 713, 728, 736, 760, 761,  
361/772, 775, 783, 820; 174/250, 253;  
438/15, 25, 26, 51, 55, 63, 64, 106  
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front view of a semiconductor module showing my new design;

FIG. 2 is a rear view thereof;

FIG. 3 is a left side view thereof;

FIG. 4 is a right side view thereof;

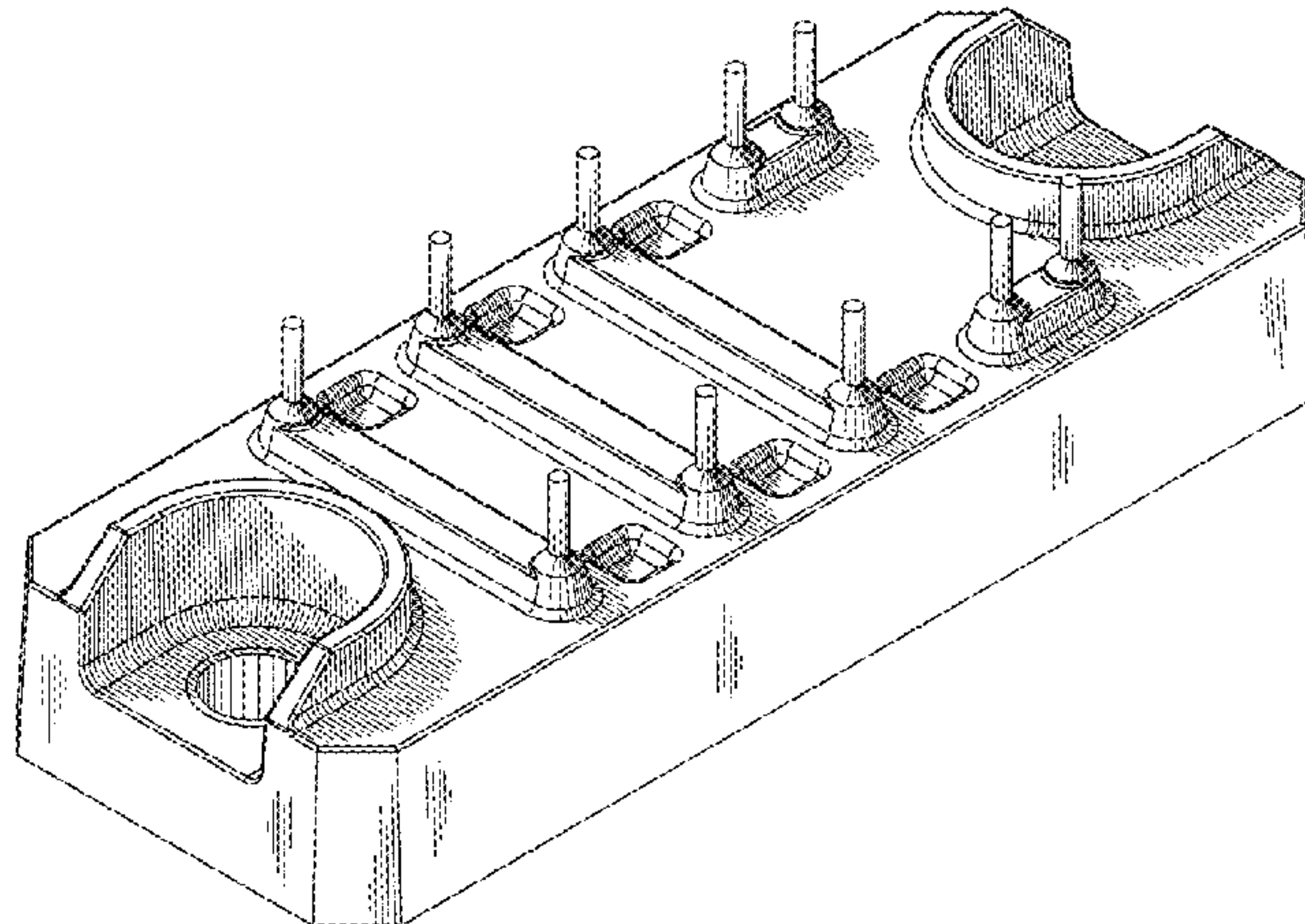
FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof; and,

FIG. 7 is a perspective view thereof.

The ornamental design of the present disclosure is a semiconductor module on which power semiconductor elements and the like may be mounted.

**1 Claim, 7 Drawing Sheets**



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Fig. 1

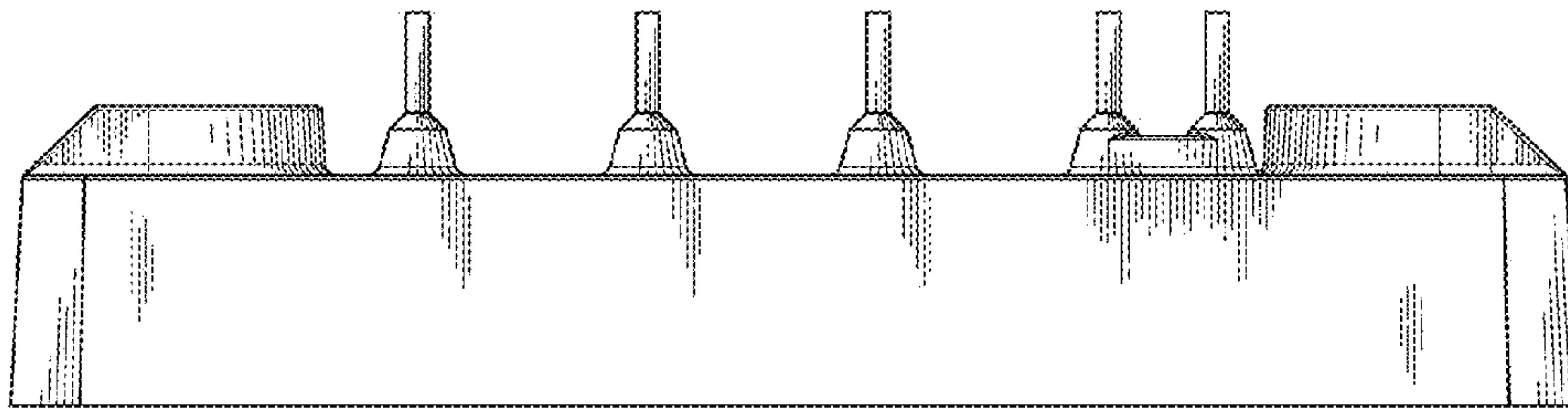


Fig. 2

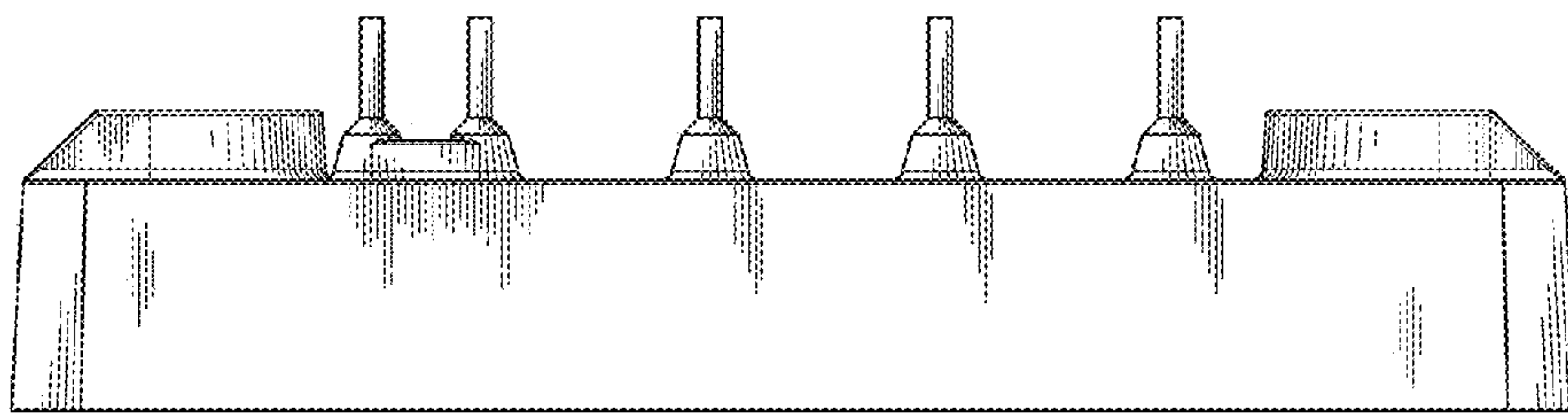


Fig. 3

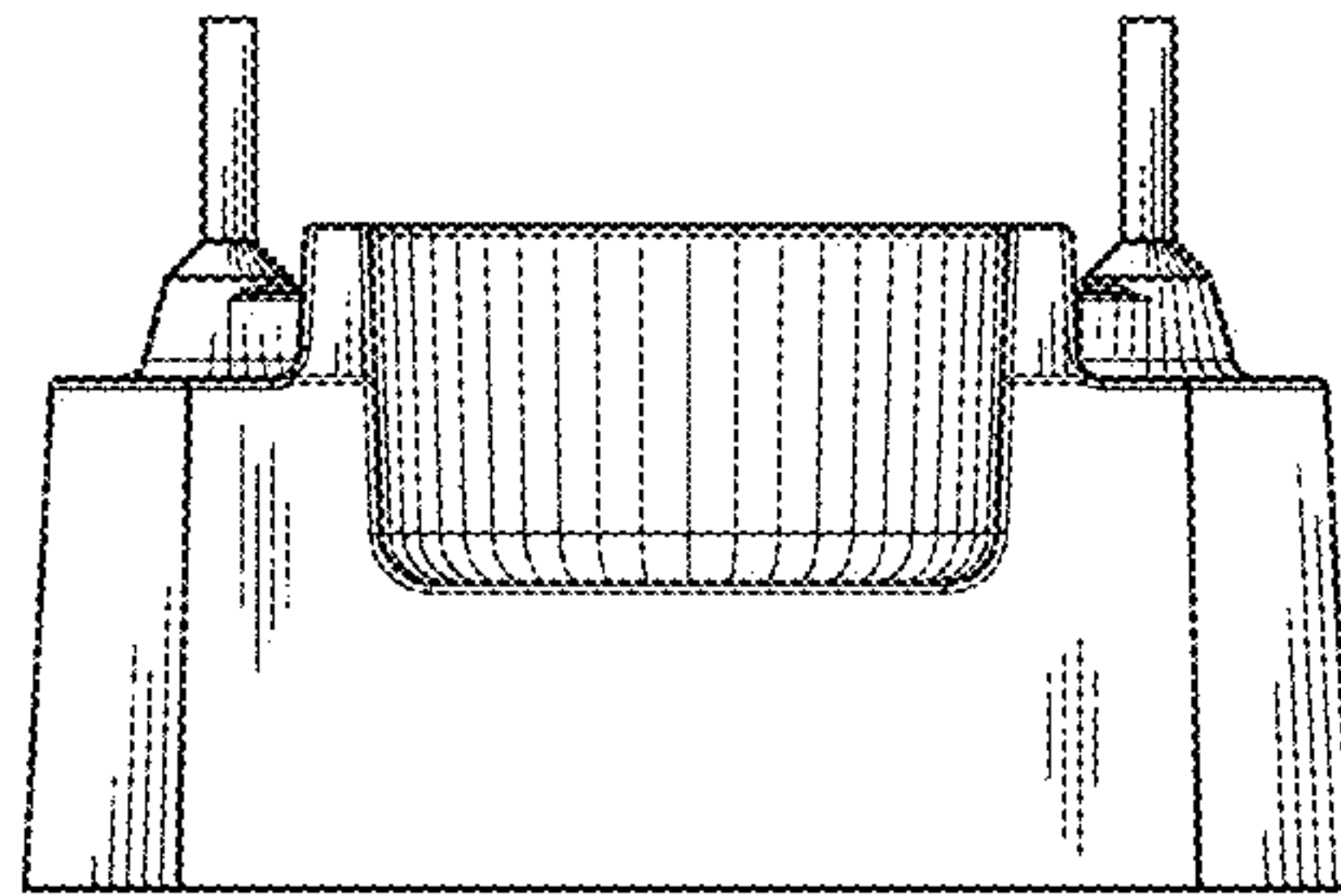


Fig. 4

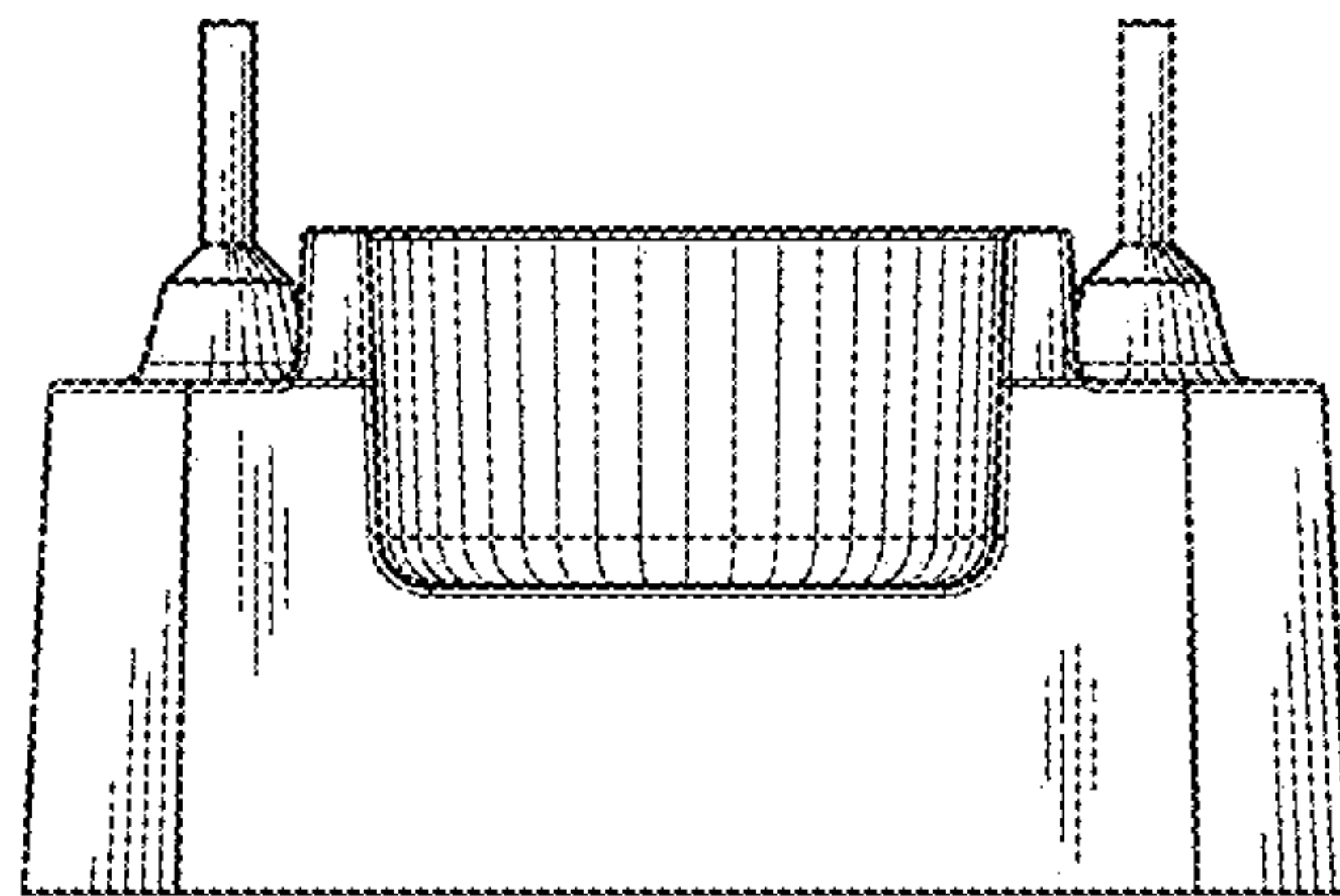




Fig. 5

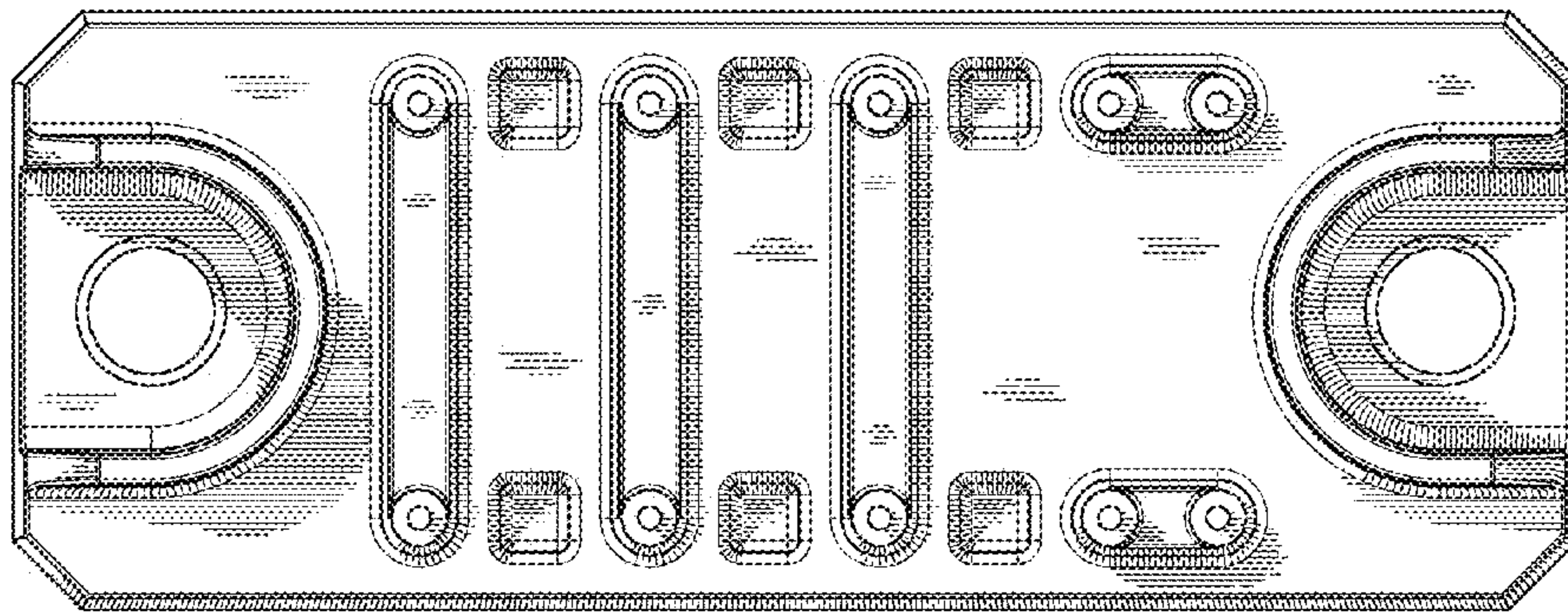


Fig. 6

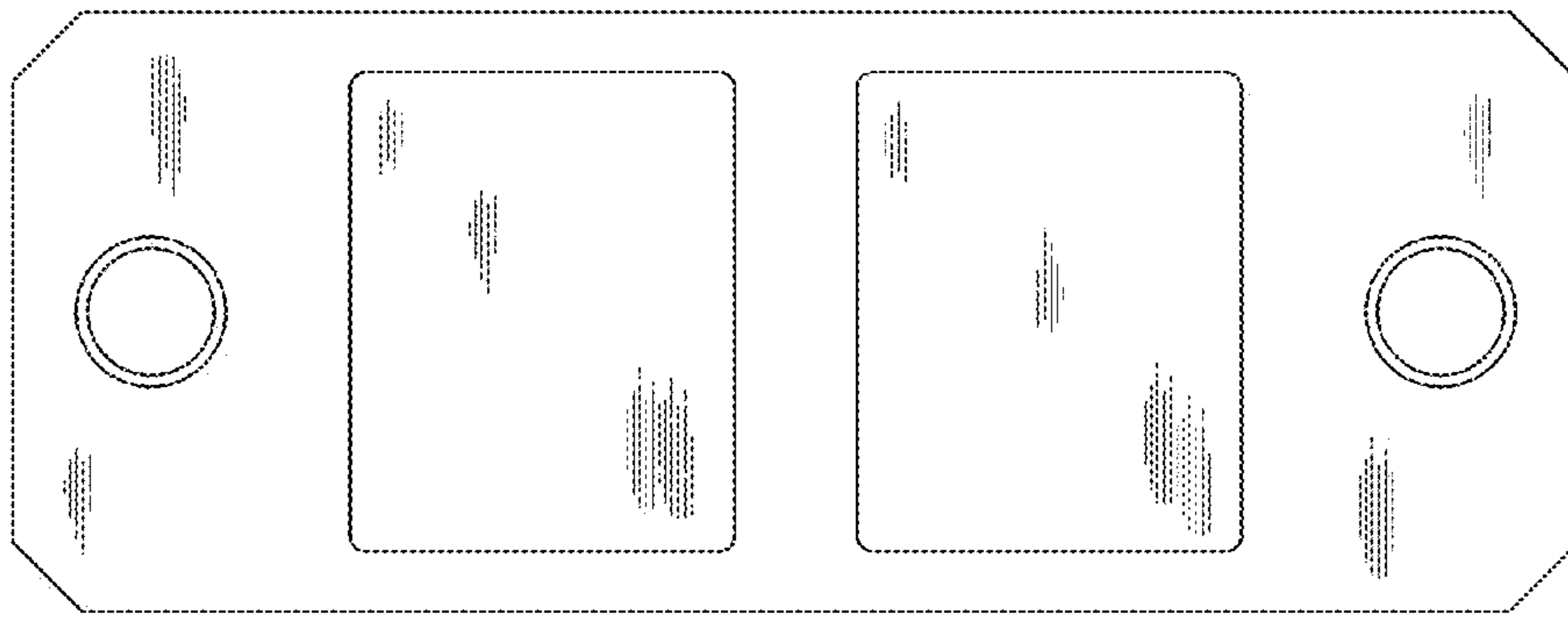




Fig. 7

